

Call for Papers

Austrochip is an annual workshop on microelectronics and integrated circuits in Austria and neighboring countries. The 25th edition will be organized by the Institute for Integrated Circuits of Johannes Kepler University in Linz.

Topics of the workshop include but are not limited to:

- Analog, mixed-signal, and RF integrated circuits
- Digital circuits, filters, DSPs, asynchronous designs
- FPGA design and reconfigurable hardware
- Design methodology, system-level design, gigascale circuits, network-on-chip
- Embedded systems, low-power designs, RF systems, security aspects
- Verification and testing, signal integrity, device modelling, timing analysis, reliability simulation, EMC, ESD
- Emerging technologies, nano CMOS process, sub-threshold circuits, sensors, organic and biomedical electronics
- Case studies and prototyping

Submissions from academia as well as industry are welcome. Especially, PhD-Students are invited to present their research work related to topics of Austrochip, but also excellent MSc-Theses will be considered.

Submissions will be double-blind-reviewed. Accepted papers will be made available electronically at the conference (USB-stick) and we plan to publish all papers written in English through IEEE Xplore (with indexing by well-known major indexing services).

Instructions for Authors:

Papers should not exceed 6 pages IEEE format (including bibliography and appendix). Instructions and additional details can be found at <http://riic.jku.at/austrochip/submission>

Conference Venue:

Austrochip 2017 is held in Linz on October 12th, 2017 at the Johannes Kepler University. Registered participants will be provided with proceedings USB stick, lunch and coffee breaks.

Contact/Organization:

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Conference Venue



Important Dates

Submission Deadline
July 3rd, 2017

Acceptance Notification
August 28th, 2017

Workshop
October 12th, 2017

Organizer



[IIC – Institute for Integrated Circuits](#)

Technical co-sponsors



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